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Index of products and services

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3 Electronics assembly and packaging, system integration

- 3.1 Electronics assembly and packaging
 - 3.1.1 Flip chip
 - 3.1.2 Other electrical contacting
- 3.2 Lamination
- 3.3 System integration
- 3.4 Hybrid systems (polytronics)

4 Inspection and test systems

- 4.1 Electrical characterization
- 4.2 Physical/optical characterization
- 4.3 Chemical characterization
- 4.4 Simulation/circuit optimization
- 4.5 Lifetime testing
- 4.6 Quality/process control
- 4.7 Environmental testing
- 4.8 Other inspection and test systems

5 Devices

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- 5.2 Diodes
- 5.3 Passive components
 - 5.3.1 Capacitors
 - 5.3.2 Resistors
 - 5.3.3 Other passives
- 5.4 Integrated circuits
- 5.5 Displays
 - 5.5.1 OLED
 - 5.5.2 Electrophoretic displays
 - 5.5.3 Electrochromic displays
 - 5.5.4 Electroluminescent displays
 - 5.5.5 LCD
 - 5.5.6 Electrowetting
 - 5.5.7 Other displays
- 5.6 Photovoltaic cells
 - 5.6.1 Organic photovoltaics
 - 5.6.2 Hybrid photovoltaics
 - 5.6.3 Inorganic photovoltaics

5.7 Sensors

- 5.7.1 Photodiodes
- 5.7.2 Pressure sensors
- 5.7.3 Temperature sensors
- 5.7.4 Biomedical sensors
- 5.7.5 Gas sensors
- 5.7.6 Touch sensors
- 5.7.7 Other sensors
- 5.8 Memory elements
- 5.9 Antennas
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- 5.11 Components for hybrid systems
- 5.12 Other devices

6 Applications

- 6.1 TFT backplanes
- 6.2 Displays
- 6.3 Sensors
- 6.4 Smart systems
- 6.5 RFID
- 6.6 Solar cells
- 6.7 Smart textiles
- 6.8 Speakers
- 6.9 Lighting
- 6.10 Other applications

7 Services

- 7.1 Consulting
- 7.2 R&D funding program management
- 7.3 R&D/Research & Development
- 7.4 Prototyping
- 7.5 Manufacturing
- 7.6 Venture and equity capitalization
- 7.7 Professional and trade associations
- 7.8 Technical books, technical journals, technical publishers
- 7.9 Other services